Chip Installation





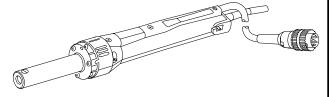
Process Guide I-CHP-00-A

Solder Paste





Mini ThermoJet **Handpiece**



EQUIPMENT REQUIRED PACE PART NUMBER

PACE SensaTemp® Power Supply With Pressure Capability - - - - - -

TJ-70 Mini ThermoJet® 7023-0002-P1 TJ-70 Tip & Tool Stand 6019-0044

Mini Thermojet Tip See chart on back

Pik & Paste Liquid Dispensing System 8007-0157 1100-0296 Tip Tool

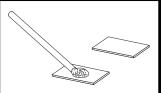
Tweezers Locally obtained

OPTIONAL EQUIPMENT

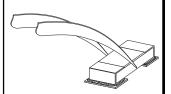
Manual Solder Paste Dispenser Locally obtained

MATERIALS (approved by your organization)

Solder Paste Locally obtained Cleaner Locally obtained Solder Paste Dispense Needles Locally obtained Tissue/wipe Locally obtained



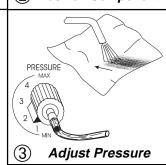
Apply Solder



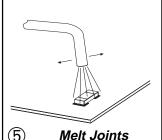
(2) Position Component

PROCEDURE

- 1. Start with a heater temperature of 427°C (800°F) and adjust as necessary.
- 2. Install Mini Thermojet Tip into ThermoJet Handpiece using Tip Tool.
- 3. Apply a small bead of solder paste to each land using a dispenser. ①
- 4. Position component onto lands using tweezers. 2
- 5. Starting at MINIMUM, adjust pressure output (on power supply) so hot air scorches a tissue from approximately 0.5cm (0.2") away. ③
- 6. Direct hot air over component with tip at a distance of 2.5cm (1.0") to predry solder paste. 4
- 7. When pre-drying is observed (paste has dull, flat appearance), move tip closer (0.5cm [0.2"]) and heat until complete solder melt is observed. ⑤
- 8. Return ThermoJet to its Tip & Tool Stand.
- 9. Clean, if required, and inspect.







TIP	DESCRIPTION	TIP SIZE	PART NUMBER
	Small, Straight, Single Jet Tip		1121-0366
	Small, Curved Single Jet Tip		1121-0338
NA L	SOT/Chip Component Tip (dual-jet)	A = 0.14" (3.56mm)	1121-0329
	SOIC Tip (dual-jet)	A = 0.17" (4.32mm)	1121-0330
	SOICL Tip (dual-jet)	A = 0.37" (9.40mm)	1121-0331
A B	Flat End Tip	A = 0.28" (7.11mm) B = 0.074" (1.88mm)	1121-0365
		A = 0.24" (6.10mm) B = 0.074" (1.88mm)	1121-0371